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uA7805, uA7808, uA7810 uA7812, uA7815, uA7824

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µA78xx Fixed Positive Voltage Regulators

Technical

Documents

1 Features

- 3-Terminal Regulators
- Available in fixed 5-V/8-V/10-V/12-V/15-V/24-V options
- Output Current up to 1.5 A
- Internal Thermal-Overload Protection
- High Power-Dissipation Capability
- Internal Short-Circuit Current Limiting
- Output Transistor Safe-Area Compensation
- Output Capacitor Not Needed for Stability

2 Applications

- On-card Regulation
- Portable Devices
- Computing & Servers
- Telecommunications

3 Description

Tools &

Software

This series of fixed-voltage integrated-circuit voltage regulators is designed for a wide range of applications. These applications include on-card regulation for elimination of noise and distribution problems associated with single-point regulation. Each of these regulators can deliver up to 1.5 A of output current. The internal current-limiting and thermal-shutdown features of these regulators essentially make them immune to overload. In addition to use as fixed-voltage regulators, these devices can be used with external components to obtain adjustable output voltages and currents, and also can be used as the power-pass element in precision regulators.

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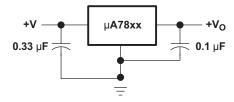
2.2

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)					
	TO-220 (3)	10.16 mm x 8.82 mm					
µA78xx	TO-220 (3)	10.16 mm x 8.82 mm					
	TO-263 (3)	10.06 mm x 9.02 mm					

(1) For all available packages, see the orderable addendum at the end of the data sheet.

4 Simplified Schematic



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5 Revision History

Changes from Revision O (August 2012) to Revision P

•	Added Applications, Device Information table, Pin Functions table, ESD Ratings table, Thermal Information table,	
	Typical Characteristics, Feature Description section, Device Functional Modes, Application and Implementation	
	section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and	
	Mechanical, Packaging, and Orderable Information section.	. 1
•	Deleted Ordering Information table.	. 1

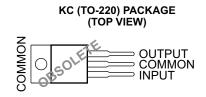
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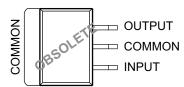
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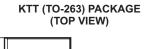
6 Pin Configuration and Functions

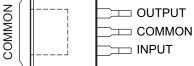


KTE (PowerFLEX™) PACKAGE (TOP VIEW)



KCS OR KCT (TO-220) PACKAGE (TOP VIEW)





Pin Functions

P	IN	TYPE	DESCRIPTION
NAME	NO.	TIPE	DESCRIPTION
COMMON	2	—	Ground
INPUT	1	I	Supply Input
OUTPUT	3	0	Voltage Output

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7 Specifications

7.1 Absolute Maximum Ratings

over virtual junction temperature range (unless otherwise noted)

			MIN	MAX	UNIT
N/	Innut voltogo	μA7824C		40	V
VI	Input voltage	All others		35	v
TJ	Operating virtual junction temperature			150	°C
	Lead temperature	1,6 mm (1/16 in) from case for 10 s		260	°C
T _{stg}	Storage temperature range		-65	150	°C

7.2 ESD Ratings

			VALUE	UNIT
		Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾	3000	
V _{(ESD}	b) Electrostatic discharge	Charged device model (CDM), per JEDEC specification JESD22-C101, all $\ensuremath{pins^{(2)}}$	2000	V

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

	· · · · · · · · · · · · · · · · · · ·		MIN	MAX	UNIT
		μΑ7805	7	25	
VI		μΑ7808	10.5	25	
	Input voltogo	μA7810	12.5	28	
	Input voltage	μA7812	14.5	30	V
		μA7815	17.5	30	
		μΑ7824	27	38	
I _O	Output current			1.5	А
TJ	Operating virtual junction temperature		0	125	°C

7.4 Thermal Information

			μΑ78ΧΧ			
THERMAL METRIC ⁽¹⁾		KTE	KCS, KCT, KC	КТТ	UNIT	
		3 PINS	3 PINS	3 PINS		
$R_{\theta JA}$	Junction-to-ambient thermal resistance	23	19	25.3		
R _{0JC(top)}	Junction-to-case (top) thermal resistance	3	17	18	°C/W	
R _{0JP(top)}	Junction-to-exposed-pad thermal resistance	2.7	3	1.94		

(1) For more information about traditional and new thermal metrics, see the IC Package Thermal Metrics application report (SPRA953).

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7.5 Electrical Characteristics — uA7805

at specified virtual junction temperature, V_I = 10 V, I_O = 500 mA (unless otherwise noted)

	TEAT CONDITIONS	T (1)	μ	A7805C			
PARAMETER	TEST CONDITIONS	T _J ⁽¹⁾	MIN	TYP	MAX	UNIT	
Output valtage	$I_0 = 5 \text{ mA to 1 A}, V_1 = 7 \text{ V to 20 V},$	25°C	4.8	5	5.2	V	
Output voltage	P _D ≤ 15 W	0°C to 125°C	4.75		5.25	v	
	$V_1 = 7 V \text{ to } 25 V$	05%0		3	100		
put voltage regulation	$V_{I} = 8 V \text{ to } 12 V$	25°C		1	50	mV	
Displayer is sting (2)	V _I = 8 V to 12 V, f = 120 Hz	- 0°C to 125°C	62	78			
Ripple rejection ⁽²⁾	V _I = 8 V to 12 V, f = 120 Hz (KCT)	0.0 125.0		68		dB	
Output voltage regulation	I _O = 5 mA to 1.5 A	0500		15	100	mV	
	I _O = 250 mA to 750 mA	25°C		5	50		
Output resistance	f = 1 kHz	0°C to 125°C		0.017		Ω	
Temperature coefficient of output voltage	I _O = 5 mA	0°C to 125°C		-1.1		mV/°C	
Output noise voltage	f = 10 Hz to 100 kHz	25°C		40		μV	
Dropout voltage	I _O = 1 A	25°C		2		V	
Bias current		25°C		4.2	8	mA	
Diag aurorat altagana	$V_1 = 7 V \text{ to } 25 V$	000 to 40500			1.3		
Bias current change	$I_{O} = 5 \text{ mA to 1 A}$	- 0°C to 125°C			0.5	mA	
Short-circuit output current		25°C		750		mA	
Peak output current		25°C		2.2		А	

(1) Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-µF capacitor across the input and a 0.1-µF capacitor across the output.

(2) This parameter is validated by design and verified during product characterization. It is not tested in production.

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7.6 Electrical Characteristics — uA7808

at specified virtual junction temperature, $V_1 = 14$ V, $I_0 = 500$ mA (unless otherwise noted)

DADAMETED		T (1)	μΑ7808C			
PARAMETER	TEST CONDITIONS	T _J ⁽¹⁾	MIN	TYP	MAX	UNIT
Output veltage	$I_{O} = 5 \text{ mA to } 1 \text{ A}, V_{I} = 10.5 \text{ V to } 23 \text{ V},$	25°C	7.7	8	8.3	V
Output voltage	P _D ≤ 15 W	0°C to 125°C	7.6		8.4	v
	V _I = 10.5 V to 25 V	25%0		6	160	m)/
Input voltage regulation	V _I = 11 V to 17 V	25°C		2	80	mV
	V _I = 11.5 V to 21.5 V, f = 120 Hz		55	72		
Ripple rejection ⁽²⁾	V _I = 11.5 V to 21.5 V, f = 120 Hz (KCT)	0°C to 125°C		62		dB
Output voltage regulation	I _O = 5 mA to 1.5 A	25°C -		12	160	mV
	I _O = 250 mA to 750 mA			4	80	
Output resistance	f = 1 kHz	0°C to 125°C		0.016		Ω
Temperature coefficient of output voltage	I _O = 5 mA	0°C to 125°C		-0.8		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz	25°C		52		μV
Dropout voltage	I _O = 1 A	25°C		2		V
Bias current		25°C		4.3	8	mA
Diag gument change	V _I = 10.5 V to 25 V	0°C to 405°C			1	mA
Bias current change	$I_{O} = 5 \text{ mA to } 1 \text{ A}$	0°C to 125°C			0.5	
Short-circuit output current		25°C		450		mA
Peak output current		25°C		2.2		А

(1) Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-µF capacitor across the input and a 0.1-µF capacitor across the output.

(2) This parameter is validated by design and verified during product characterization. It is not tested in production.

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7.7 Electrical Characteristics — uA7810

at specified virtual junction temperature, $V_1 = 17$ V, $I_0 = 500$ mA (unless otherwise noted)

DADAMETED	TEST CONDITIONS	T _J ⁽¹⁾	μA7810C			
PARAMETER	TEST CONDITIONS	IJ (''	MIN	TYP	MAX	UNIT
Output voltage	$I_{O} = 5$ mA to 1 A, $V_{I} = 12.5$ V to 25 V,	25°C	9.6	10	10.4	V
Ouiput voltage	P _D ≤ 15 W	0°C to 125°C	9.5		10.5	v
Input voltage regulation	V _I = 12.5 V to 28 V	25%0		7	200	mV
Input voltage regulation	V _I = 14 V to 20 V	25°C -		2	100	mv
Ripple rejection ⁽²⁾	V _I = 13 V to 23 V, f = 120 Hz	0°C to 125°C	55	71		dB
Output voltage regulation	I _O = 5 mA to 1.5 A	05%0		12	200	mV
	I _O = 250 mA to 750 mA	25°C		4	100	
Output resistance	f = 1 kHz	0°C to 125°C		0.018		Ω
Temperature coefficient of output voltage	$I_{O} = 5 \text{ mA}$	0°C to 125°C		-1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz	25°C		70		μV
Dropout voltage	I _O = 1 A	25°C		2		V
Bias current		25°C		4.3	8	mA
Dies ourrest shange	V _I = 12.5 V to 28 V	0°C to 125°C			1	~ ^
Bias current change	$I_{O} = 5 \text{ mA to } 1 \text{ A}$	0.010125.0			0.5	mA
Short-circuit output current		25°C		400		mA
Peak output current		25°C		2.2		А

(1) Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-µF capacitor across the input and a 0.1-µF capacitor across the output.

This parameter is validated by design and verified during product characterization. It is not tested in production. (2)

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7.8 Electrical Characteristics — uA7812

at specified virtual junction temperature, $V_1 = 19 V$, $I_0 = 500 mA$ (unless otherwise noted)

BADAMETER	TEAT CONDITIONS	T (1)	μ				
PARAMETER	TEST CONDITIONS	T _J ⁽¹⁾	MIN	TYP MAX		UNIT	
	$I_{O} = 5 \text{ mA to } 1 \text{ A}, V_{I} = 14.5 \text{ V to } 27 \text{ V},$	25°C	11.5	12	12.5	V	
Output voltage	P _D ≤ 15 W	0°C to 125°C	11.4		12.6	v	
Input veltage regulation	V _I = 14.5 V to 30 V	25°C		10	240	~\/	
Input voltage regulation	V _I = 16 V to 22 V	25°C		3	120	mV	
Ripple rejection ⁽²⁾	$V_{I} = 15 V$ to 25 V, f = 120 Hz	0°C to 125°C	55	71		dB	
Ripple rejection/	V _I = 15 V to 25 V, f = 120 Hz (KCT)	0.0125.0		61		uБ	
Output voltage regulation	I _O = 5 mA to 1.5 A		12	240	mV		
	I _O = 250 mA to 750 mA	25°C		4	120	mv	
Output resistance	f = 1 kHz	0°C to 125°C		0.018		Ω	
Temperature coefficient of output voltage	I _O = 5 mA	0°C to 125°C		-1		mV/°C	
Output noise voltage	f = 10 Hz to 100 kHz	25°C		75		μV	
Dropout voltage	I _O = 1 A	25°C		2		V	
Bias current		25°C		4.3	8	mA	
	V _I = 14.5 V to 30 V	0%C to 405%C			1		
Bias current change	$I_0 = 5 \text{ mA to 1 A}$	0°C to 125°C			0.5	mA	
Short-circuit output current		25°C		350		mA	
Peak output current		25°C		2.2		А	

(1) Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-µF capacitor across the input and a 0.1-µF capacitor across the output.

(2) This parameter is validated by design and verified during product characterization. It is not tested in production.

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7.9 Electrical Characteristics — uA7815

at specified virtual junction temperature, V_I = 23 V, I_O = 500 mA (unless otherwise noted)

DADAMETED		T (1)	μ	A7815C			
PARAMETER	TEST CONDITIONS	T _J ⁽¹⁾	MIN	TYP MAX		UNIT	
	$I_{O} = 5 \text{ mA to } 1 \text{ A}, V_{I} = 17.5 \text{ V to } 30 \text{ V},$	25°C	14.4	15	15.6	V	
Output voltage	P _D ≤ 15 W	0°C to 125°C	14.25		15.75	v	
	V _I = 17.5 V to 30 V	25%		11	300	m)/	
Input voltage regulation	$V_{I} = 20 V \text{ to } 26 V$	25°C		3	150	mV	
	V _I = 18.5 V to 28.5 V, f = 120 Hz		54	70			
Ripple rejection ⁽²⁾	V _I = 18.5 V to 28.5 V, f = 120 Hz (KCT)	0°C to 125°C		60		dB	
Output voltage regulation	I _O = 5 mA to 1.5 A	25%0		12	300		
	I _O = 250 mA to 750 mA	25°C		4	150	mV	
Output resistance	f = 1 kHz	0°C to 125°C		0.019		Ω	
Temperature coefficient of output voltage	I _O = 5 mA	0°C to 125°C		-1		mV/°C	
Output noise voltage	f = 10 Hz to 100 kHz	25°C		90		μV	
Dropout voltage	I _O = 1 A	25°C		2		V	
Bias current		25°C		4.4	8	mA	
Diag ourrent change	V _I = 17.5 V to 30 V	0°C to 125°C			1	~ ^	
Bias current change	$I_{O} = 5 \text{ mA to } 1 \text{ A}$	0°C to 125°C			0.5	mA	
Short-circuit output current		25°C		230		mA	
Peak output current		25°C		2.1		А	

(1) Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-µF capacitor across the input and a 0.1-µF capacitor across the output.

(2) This parameter is validated by design and verified during product characterization. It is not tested in production.

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7.10 Electrical Characteristics — uA7824

at specified virtual junction temperature, $V_1 = 33$ V, $I_0 = 500$ mA (unless otherwise noted)

		T (1)	μ				
PARAMETER	TEST CONDITIONS	T _J ⁽¹⁾	MIN TYP		MAX	UNIT	
Output voltage	$I_0 = 5 \text{ mA to } 1 \text{ A}, V_1 = 27 \text{ V to } 38 \text{ V},$	25°C	23	24	25	V	
Output voltage	P _D ≤ 15 W	0°C to 125°C	22.8		25.2	V	
Innut voltage regulation	V ₁ = 27 V to 38 V	25°C		18	480	m\/	
Input voltage regulation	$V_1 = 30 V \text{ to } 36 V$	2510		6	240	mV	
Ripple rejection ⁽²⁾	V _I = 28 V to 38 V, f = 120 Hz	0°C to 125°C	50	66		dB	
Output voltage regulation	I _O = 5 mA to 1.5 A	25%0		12	480	m)/	
	I _O = 250 mA to 750 mA	25°C		4	240	mV	
Output resistance	f = 1 kHz	0°C to 125°C		0.028		Ω	
Temperature coefficient of output voltage	I _O = 5 mA	0°C to 125°C		-1.5		mV/°C	
Output noise voltage	f = 10 Hz to 100 kHz	25°C		170		μV	
Dropout voltage	I _O = 1 A	25°C		2		V	
Bias current		25°C		4.6	8	mA	
Diag automatic changes	V ₁ = 27 V to 38 V	000 += 40500		1			
Bias current change	$I_{O} = 5 \text{ mA to } 1 \text{ A}$	- 0°C to 125°C			0.5	mA	
Short-circuit output current		25°C		150		mA	
Peak output current		25°C		2.1		А	

(1) Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-µF capacitor across the input and a 0.1-µF capacitor across the output.

(2) This parameter is validated by design and verified during product characterization. It is not tested in production.

7.11 Typical Characteristics

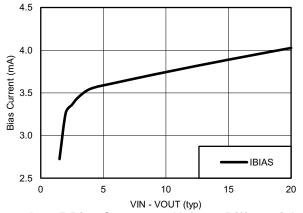


Figure 1. µA7805 Bias Current vs Voltage Differential at 25°C

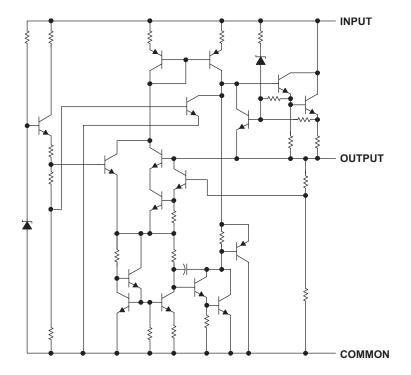


8 Detailed Description

8.1 Overview

This series of fixed-voltage integrated-circuit voltage regulators is designed for a wide range of applications. These applications include on-card regulation for elimination of noise and distribution problems associated with single-point regulation. Each of these regulators can deliver up to 1.5 A of output current. The internal current-limiting and thermal-shutdown features of these regulators essentially make them immune to overload. In addition to use as fixed-voltage regulators, these devices can be used with external components to obtain adjustable output voltages and currents, and also can be used as the power-pass element in precision regulators.

8.2 Functional Schematic



8.3 Feature Description

8.3.1 Thermal Overload

When the die temperature increases to unwanted levels, the device will reduce the output current to lower its temperature. Under heavy loads, the device may alternate between on and off output states to regulate temperature.

8.3.2 Short-Circuit Current Limiting

In the event of a short circuit, the device will limit its own current to safe levels by lowering the bias voltage of internal pass transistors. If the device becomes overheated, the thermal overload protection will take over.

8.4 Device Functional Modes

8.4.1 Fixed-Output Mode

These devices are available in fixed-output voltages. See the orderable part list for the desired output.

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9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

The following section shows application details of the μ A78xx as a linear regulator.

9.2 Typical Application

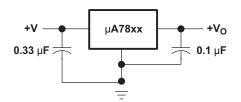


Figure 2. Fixed-Output Regulator

9.2.1 Design Requirements

- Input supply capacitor recommended for filtering noise on the input
- Output supply decoupling capacitor for stabilizing the output

9.2.2 Detailed Design Procedure

9.2.2.1 Operation With a Load Common to a Voltage of Opposite Polarity

In many cases, a regulator powers a load that is not connected to ground but, instead, is connected to a voltage source of opposite polarity (e.g., operational amplifiers, level-shifting circuits, etc.). In these cases, a clamp diode should be connected to the regulator output as shown in Figure 3. This protects the regulator from output polarity reversals during startup and short-circuit operation.

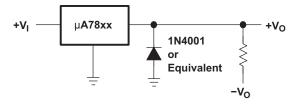


Figure 3. Output Polarity-Reversal-Protection Circuit

9.2.2.2 Reverse-Bias Protection

Occasionally, the input voltage to the regulator can collapse faster than the output voltage. This can occur, for example, when the input supply is crowbarred during an output overvoltage condition. If the output voltage is greater than approximately 7 V, the emitter-base junction of the series-pass element (internal or external) could break down and be damaged. To prevent this, a diode shunt can be used as shown in Figure 4.



Typical Application (continued)

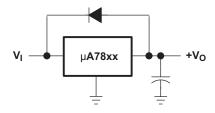


Figure 4. Reverse-Bias-Protection Circuit

9.2.3 Application Curves

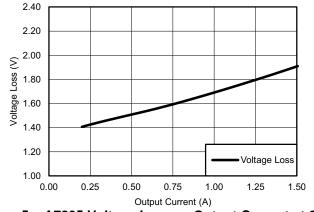


Figure 5. µA7805 Voltage Loss vs Output Current at 25°C

9.2.4 General Configurations

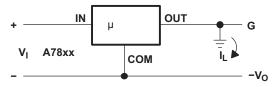
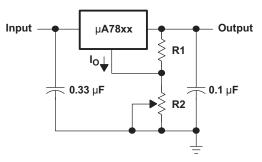
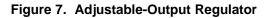


Figure 6. Positive Regulator in Negative Configuration (VI Must Float)



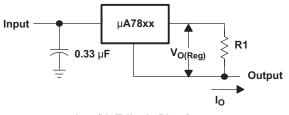
A: The following formula is used when V_{xx} is the nominal output voltage (output to common) of the fixed regulators

$$V_{o} = V_{xx} + \left(\frac{V_{xx}}{R1} + I_{o}\right)R2$$





Typical Application (continued)



I_O = (V_O/R1) + I_O Bias Current



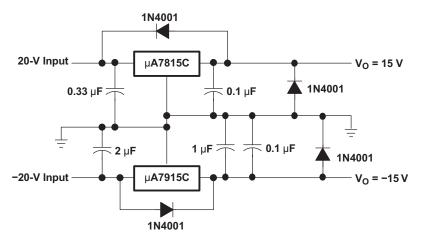


Figure 9. Regulated Dual Supply

10 Power Supply Recommendations

See *Recommended Operating Conditions* for the recommended power supply voltages for each variation of the μ A78xx device. Different orderable part numbers will be able to tolerate different levels of voltage. It is also recommended to have a decoupling capacitor on the output of the μ A78xx device's power supply to limit noise on the device input.

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Product Folder Links: uA7805 uA7808 uA7810 uA7812 uA7815 uA7824



11 Layout

11.1 Layout Guidelines

Keep trace widths large enough to eliminate problematic $I \times R$ voltage drops at the input and output terminals. Input decoupling capacitors should be placed as close to the $\mu A78XX$ as possible.

11.2 Layout Example

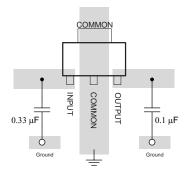


Figure 10. Layout Diagram

12 Device and Documentation Support

12.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
µA7805	Click here	Click here	Click here	Click here	Click here
uA7808	Click here	Click here	Click here	Click here	Click here
uA7810	Click here	Click here	Click here	Click here	Click here
uA7812	Click here	Click here	Click here	Click here	Click here
uA7815	Click here	Click here	Click here	Click here	Click here
uA7924	Click here	Click here	Click here	Click here	Click here

Table 1. Related Links

12.2 Trademarks

12.3 Electrostatic Discharge Caution

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.4 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.



17-Mar-2017

PACKAGING INFORMATION

Orderable Device	Status	Package Type		Pins		Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
UA7805CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7805C	Samples
UA7805CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7805C	Samples
UA7805CKCT	ACTIVE	TO-220	KCT	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7805C	Samples
UA7805CKTTR	ACTIVE	DDPAK/ TO-263	КТТ	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	0 to 125	UA7805C	Samples
UA7805CKTTRG3	ACTIVE	DDPAK/ TO-263	КТТ	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	0 to 125	UA7805C	Samples
UA7808CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7808C	Samples
UA7808CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7808C	Samples
UA7808CKCT	ACTIVE	TO-220	КСТ	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7808C	Samples
UA7808CKTTR	ACTIVE	DDPAK/ TO-263	КТТ	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	0 to 125	UA7808C	Samples
UA7808CKTTRG3	ACTIVE	DDPAK/ TO-263	КТТ	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	0 to 125	UA7808C	Samples
UA7810-W	ACTIVE	WAFERSALE	YS	0	3952	TBD	Call TI	Call TI			Samples
UA7810CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7810C	Samples
UA7810CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7810C	Samples
UA7810CKTTR	ACTIVE	DDPAK/ TO-263	КТТ	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	0 to 125	UA7810C	Samples
UA7810CKTTRG3	ACTIVE	DDPAK/ TO-263	КТТ	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	0 to 125	UA7810C	Samples
UA7812CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7812C	Samples
UA7812CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7812C	Samples



17-Mar-2017

Orderable Device	Status	Package Type		Pins	-		Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
UA7812CKCT	ACTIVE	TO-220	KCT	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7812C	Samples
UA7812CKTTR	ACTIVE	DDPAK/ TO-263	КТТ	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	0 to 125	UA7812C	Samples
UA7812CKTTRG3	ACTIVE	DDPAK/ TO-263	КТТ	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	0 to 125	UA7812C	Samples
UA7815CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7815C	Samples
UA7815CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7815C	Samples
UA7815CKCT	ACTIVE	TO-220	КСТ	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7815C	Samples
UA7815CKTTR	ACTIVE	DDPAK/ TO-263	КТТ	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	0 to 125	UA7815C	Samples
UA7824CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7824C	Samples
UA7824CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 125	UA7824C	Samples
UA7824CKTTR	ACTIVE	DDPAK/ TO-263	КТТ	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	0 to 125	UA7824C	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)



17-Mar-2017

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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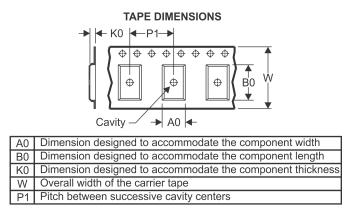
PACKAGE MATERIALS INFORMATION

www.ti.com

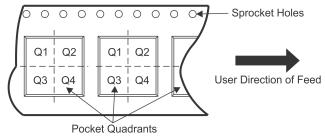
Texas Instruments

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



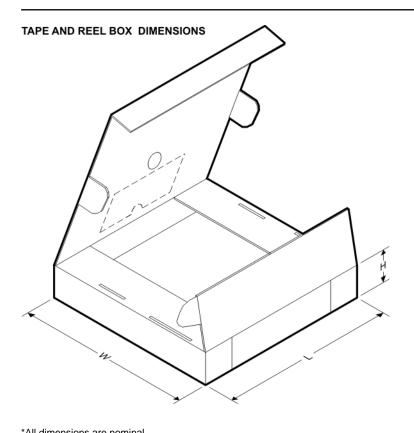
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UA7805CKTTR	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.8	16.3	5.11	16.0	24.0	Q2
UA7805CKTTR	DDPAK/ TO-263	КТТ	3	500	330.0	24.4	10.8	16.1	4.9	16.0	24.0	Q2
UA7808CKTTR	DDPAK/ TO-263	КТТ	3	500	330.0	24.4	10.8	16.3	5.11	16.0	24.0	Q2
UA7810CKTTR	DDPAK/ TO-263	КТТ	3	500	330.0	24.4	10.8	16.3	5.11	16.0	24.0	Q2
UA7812CKTTR	DDPAK/ TO-263	КТТ	3	500	330.0	24.4	10.8	16.3	5.11	16.0	24.0	Q2
UA7812CKTTR	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.8	16.1	4.9	16.0	24.0	Q2
UA7815CKTTR	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.8	16.3	5.11	16.0	24.0	Q2
UA7824CKTTR	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.8	16.3	5.11	16.0	24.0	Q2

Texas Instruments

www.ti.com

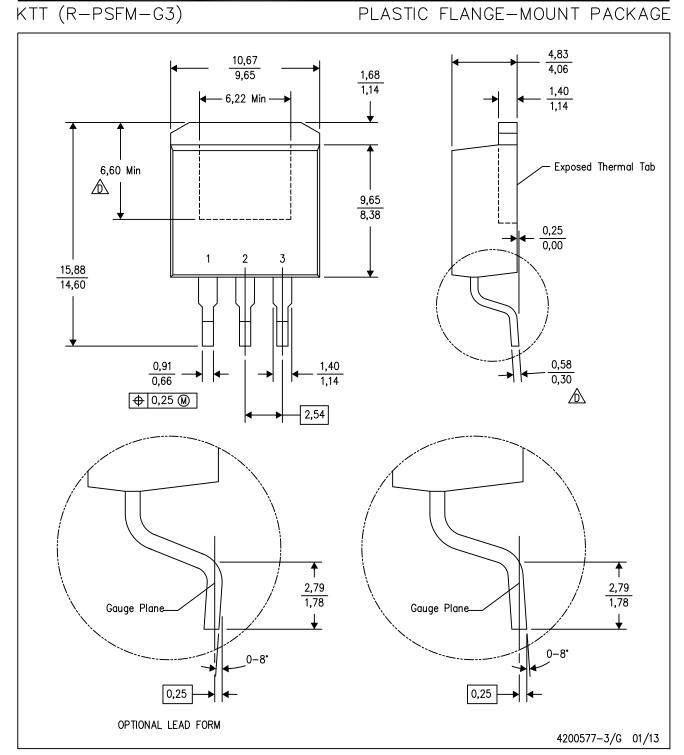
PACKAGE MATERIALS INFORMATION

21-Mar-2017



*All dimensions are nominal							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UA7805CKTTR	DDPAK/TO-263	КТТ	3	500	340.0	340.0	38.0
UA7805CKTTR	DDPAK/TO-263	КТТ	3	500	350.0	334.0	47.0
UA7808CKTTR	DDPAK/TO-263	КТТ	3	500	340.0	340.0	38.0
UA7810CKTTR	DDPAK/TO-263	КТТ	3	500	340.0	340.0	38.0
UA7812CKTTR	DDPAK/TO-263	КТТ	3	500	340.0	340.0	38.0
UA7812CKTTR	DDPAK/TO-263	КТТ	3	500	350.0	334.0	47.0
UA7815CKTTR	DDPAK/TO-263	КТТ	3	500	340.0	340.0	38.0
UA7824CKTTR	DDPAK/TO-263	КТТ	3	500	340.0	340.0	38.0

MECHANICAL DATA



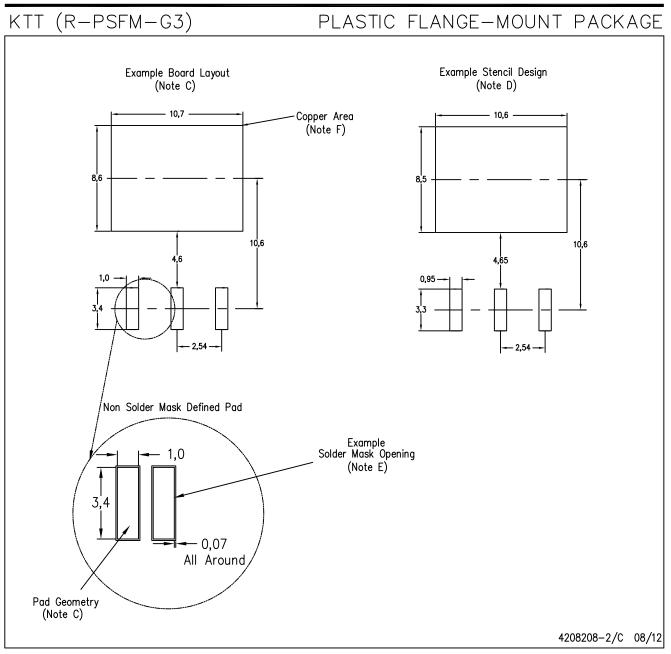
NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion. Mold flash or protrusion not to exceed 0.005 (0,13) per side.

A Falls within JEDEC TO-263 variation AA, except minimum lead thickness and minimum exposed pad length.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-SM-782 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.
- F. This package is designed to be soldered to a thermal pad on the board. Refer to the Product Datasheet for specific thermal information, via requirements, and recommended thermal pad size. For thermal pad sizes larger than shown a solder mask defined pad is recommended in order to maintain the solderable pad geometry while increasing copper area.



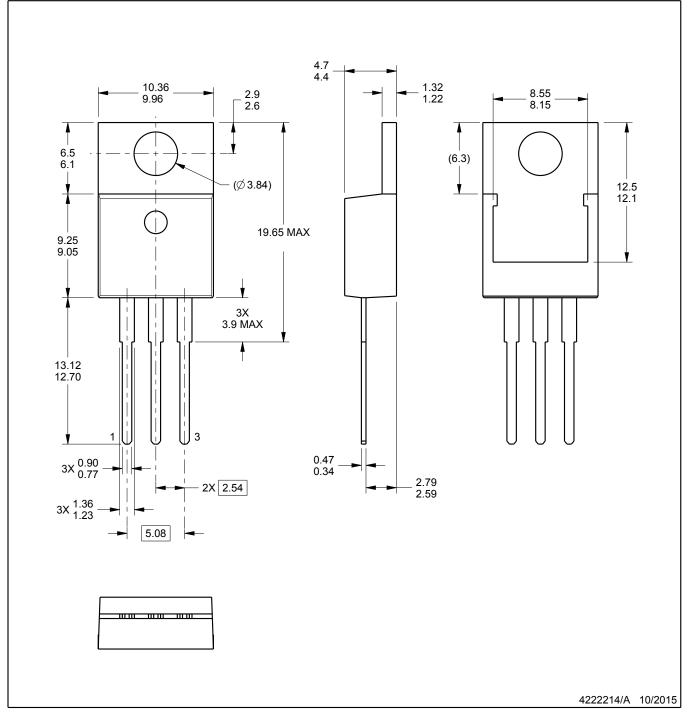
KCS0003B



PACKAGE OUTLINE

TO-220 - 19.65 mm max height

TO-220



NOTES:

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

This drawing is subject to change without notice.
Reference JEDEC registration TO-220.

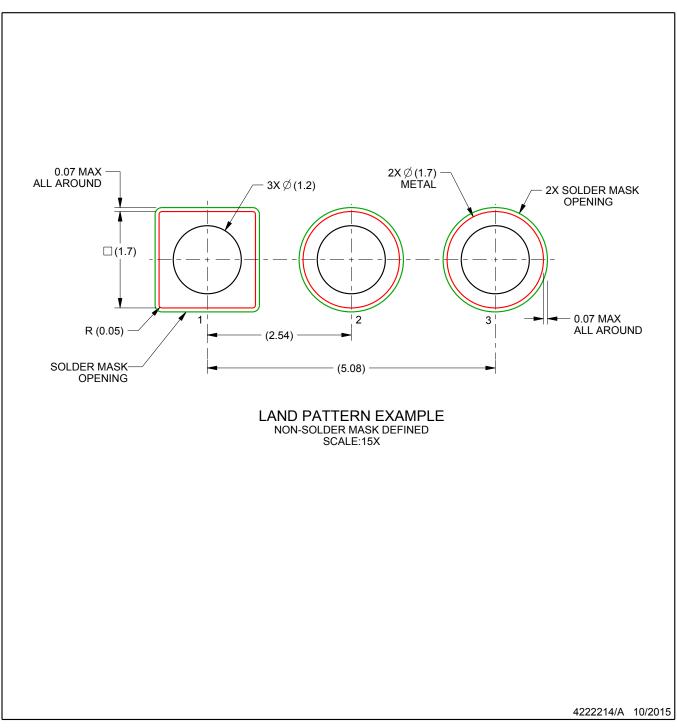


KCS0003B

EXAMPLE BOARD LAYOUT

TO-220 - 19.65 mm max height

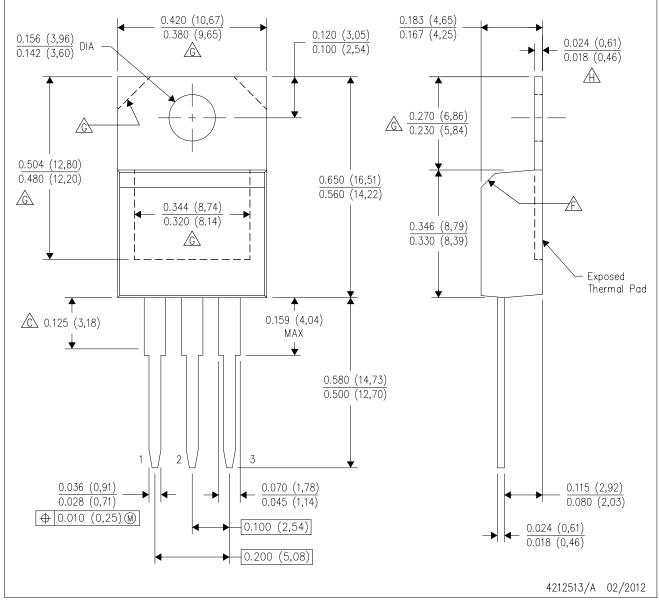
TO-220





KCT (R-PSFM-T3)

PLASTIC FLANGE-MOUNT PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Lead dimensions are not controlled within this area.
- D. All lead dimensions apply before solder dip.
- E. The center lead is in electrical contact with the mounting tab.
- $\stackrel{\frown}{\frown}$ The chamfer is optional.
- A Thermal pad contour optional within these dimensions.
- \triangle Falls within JEDEC TO-220 variation AB, except minimum tab thickness.



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